

PATENT ABSTRACTS OF JAPAN

(11)Publication number : 02-031437

(43)Date of publication of application : 01.02.1990

(51)Int.Cl.

H01L 21/60
H01L 21/56

(21)Application number : 63-182139

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(22)Date of filing :

21.07.1988

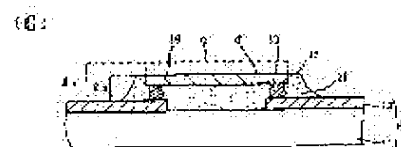
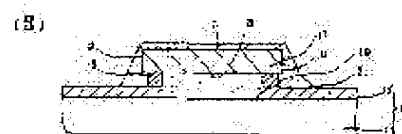
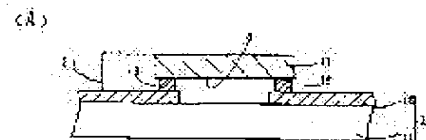
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(54) METHOD FOR PACKAGING SEMICONDUCTOR CHIP

(57)Abstract:

PURPOSE: To enhance packaging density without defectively affecting a semiconductor chip by a method wherein a semiconductor chip is bonded face down onto a circuit board and sealed in a resin and then the rear side of the chip is subjected to grinding for a reduction in the packaging height.

CONSTITUTION: A wire 13 or other components are arranged on top of a board 11 for the construction of a circuit board 15. Thereafter, through the intermediary of a bump 10, face down bonding is accomplished for the establishment of electrical connection between a driving IC 17 and the wire 13. In Fig. A, l1 is the packaging height. Next, a resin is put into between the face (a) of the driving IC 17 and the circuit board 15, and is applied to the side (b) and the rear face (c) of the driving IC 17, a resin layer 21 is formed, and the driving IC 17 is hermetically fixed to the circuit board 15 for the construction of a product in Fig. B. A process follows wherein a polisher is used for grinding the driving IC 17 from the rear face (c) for the formation of a rear face (d) wherewith the package height is reduced to l2, which completes the packaging of a semiconductor chip.



LEGAL STATUS

[Date of request for examination]

[Date of sending the examiner's decision of rejection]

[Kind of final disposal of application other than the examiner's decision of rejection or application converted registration]

[Date of final disposal for application]

[Patent number]

[Date of registration]

[Number of appeal against examiner's decision of rejection]

[Date of requesting appeal against examiner's decision of rejection]

[Date of extinction of right]

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